



Material Content Data Sheet



Sales Product Name		BSC0901NS		Issued		1. August 2018		
MA#		MA001833438						
Package		PG-TDSON-8-6		Weight*		100.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	0.67	0.67	6653	6653
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.038	0.04		375	
	non noble metal	copper	7440-50-8	37.762	37.44	37.49	374394	374881
	noble metal	gold	7440-57-5	0.045	0.04	0.04	446	446
wire	organic material	carbon black	1333-86-4	0.097	0.10		960	
encapsulation	plastics	epoxy resin	-	7.651	7.59		75862	
	inorganic material	silicondioxide	60676-86-0	40.679	40.34	48.03	403315	480137
leadfinish	non noble metal	tin	7440-31-5	1.452	1.44	1.44	14393	14393
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1641	1641
solder	non noble metal	tin	7440-31-5	0.019	0.02		189	
	noble metal	silver	7440-22-4	0.024	0.02		237	
heatspreader	non noble metal	lead	7439-92-1	0.912	0.90	0.94	9043	9469
	inorganic material	phosphorus	7723-14-0	0.003	0.00		34	
	non noble metal	iron	7439-89-6	0.011	0.01		112	
	non noble metal	copper	7440-50-8	11.320	11.22	11.23	112234	112380
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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